



SUA-110E8-30x-S242

鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"

NOTE:

1.MATERIAL:

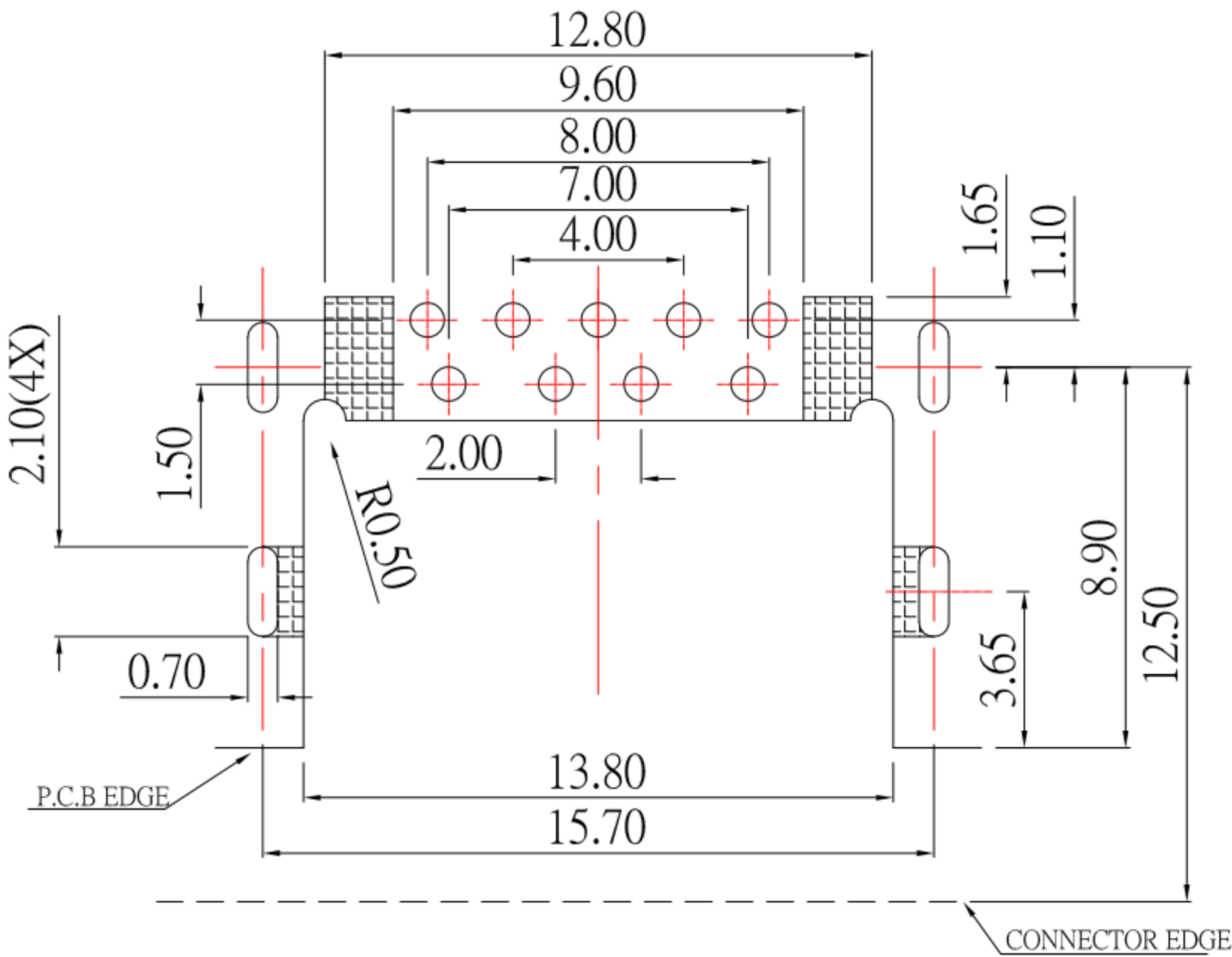
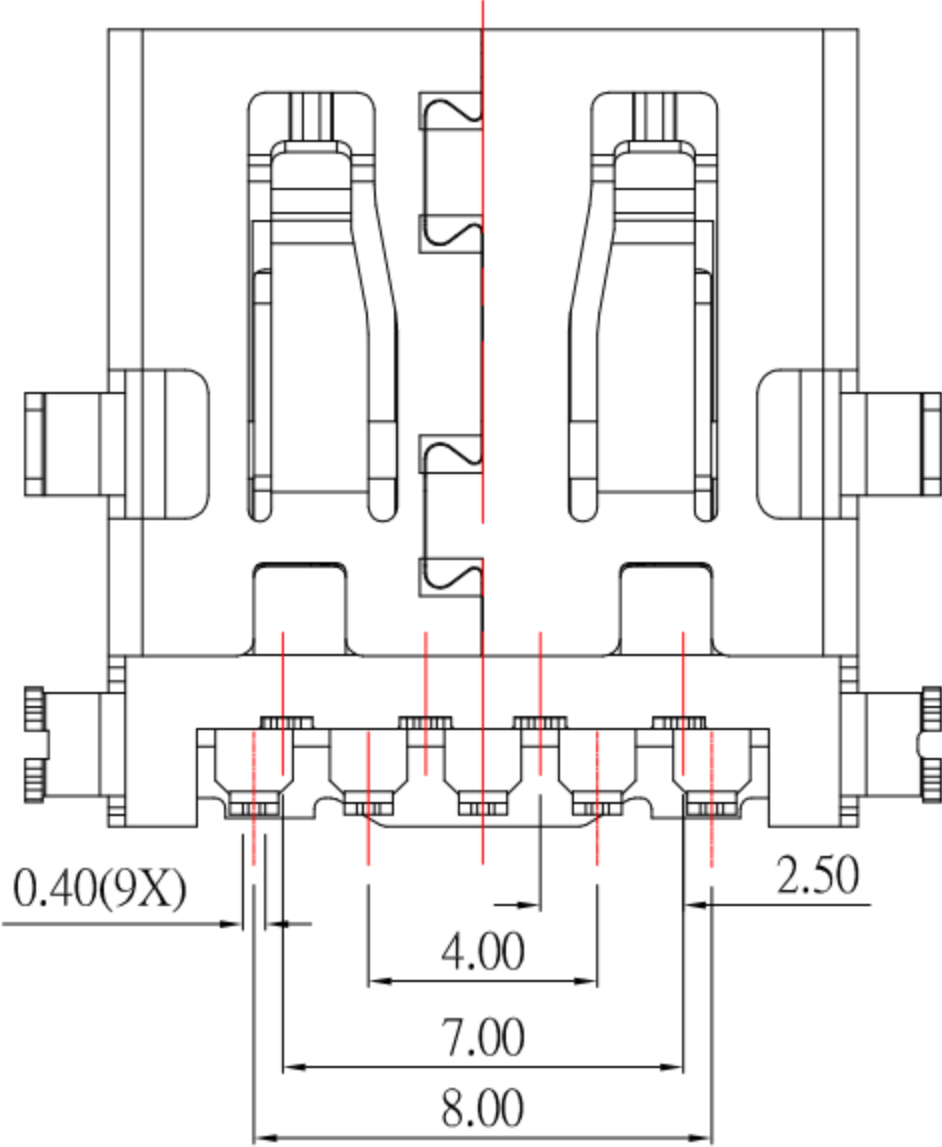
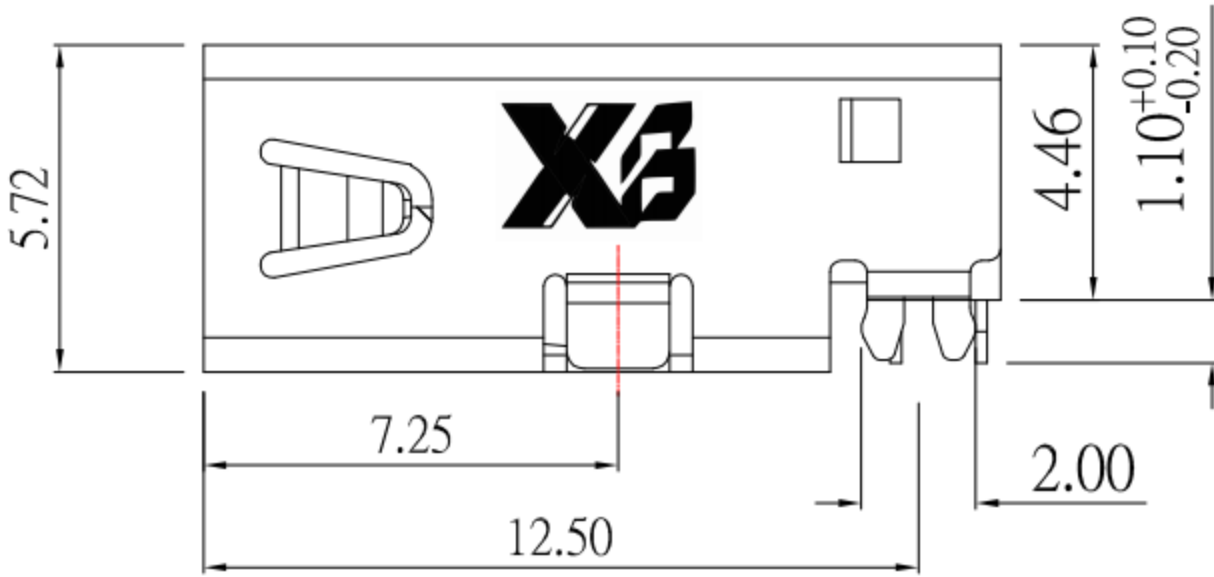
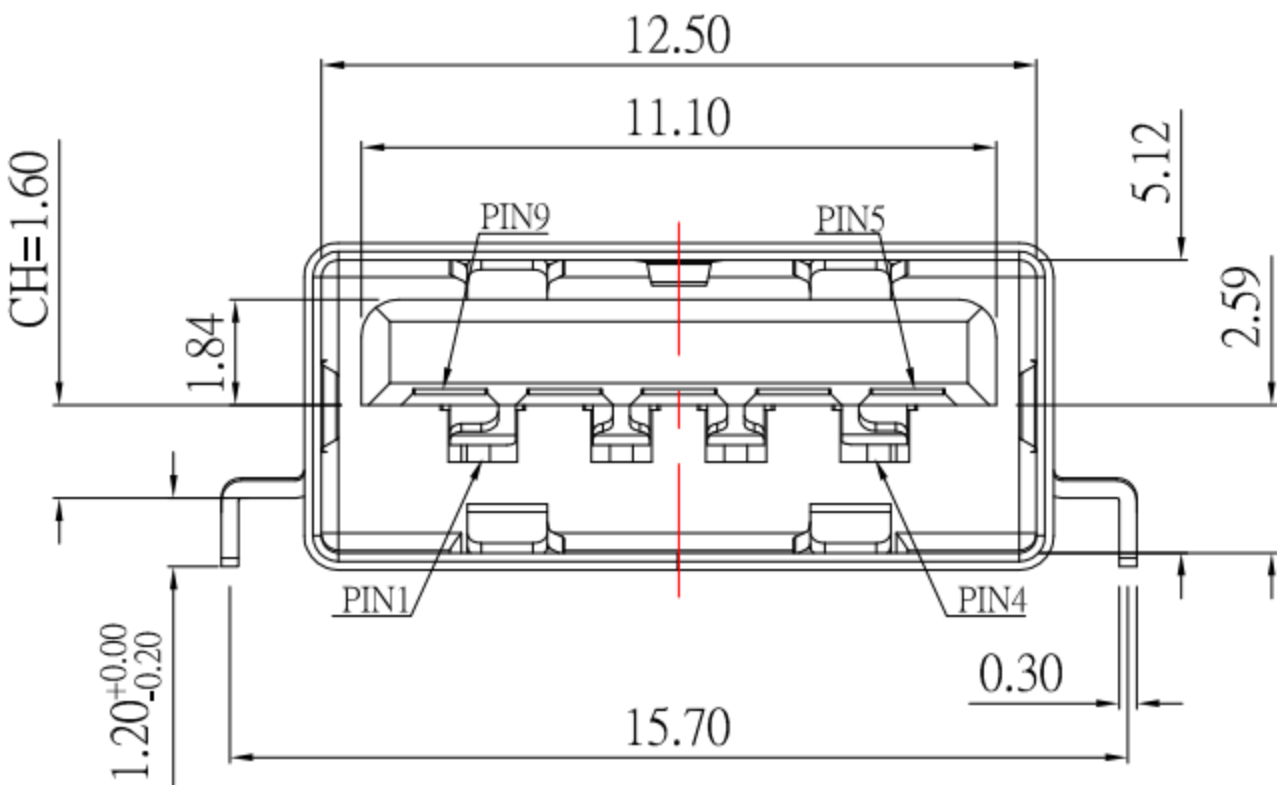
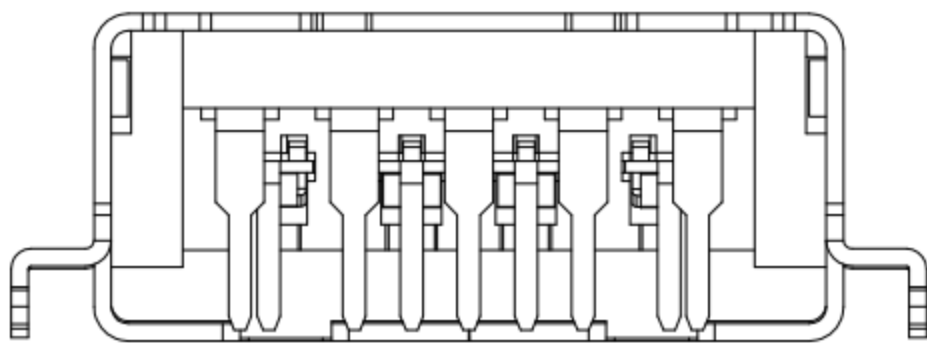
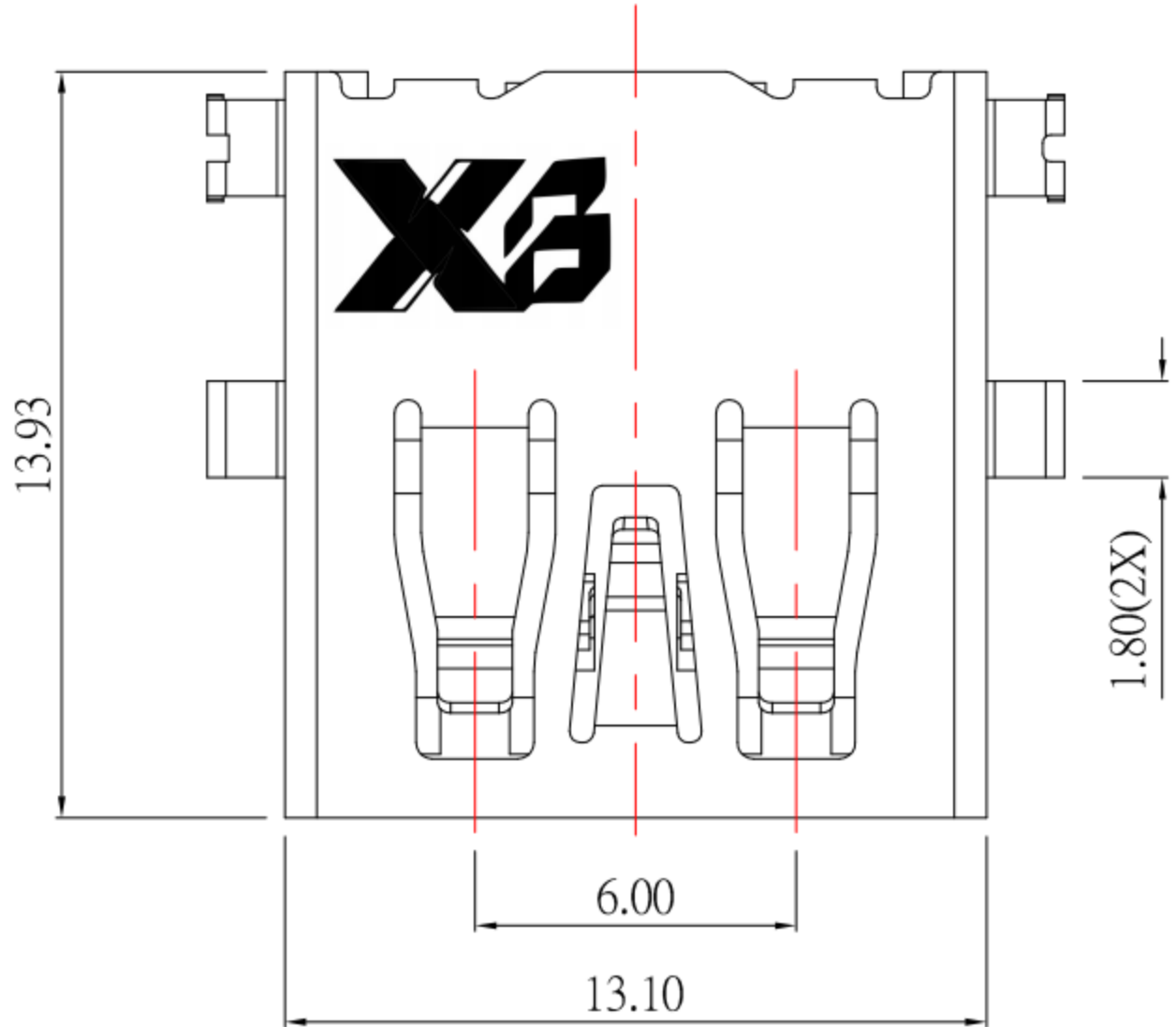
- 1.1 Housing: PBT,(UL94V-0)
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55℃ ~ +85℃
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



RECOMMENDED PCB LAYOUT
(TOP VIEW)



TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°
3RD. ANGEL'S
UNITS MM

DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR
Jack Lu	08/16/18	FINISH		MODLE	USB 3.0 A/F 沉板H:4.46 DIP ,無捲邊
CHECKED BY:	DATE	SCALE	1 : 1	DWG NO.	SUA-110E8-30x-S242
Jacky Chen	08/16/18	SHEET NO.	1 of 1	PART NO.	SUA-110E8-30x-S242
APPROVED BY:	DATE				
Tony Kao	08/16/18				